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# Is Now



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# **Dual Inverter, Open Drain**

The NLU2G06 MiniGate  $^{\text{m}}$  is an advanced high-speed CMOS dual inverter with open drain output in ultra-small footprint.

The NLU2G06 input and output structures provide protection when voltages up to 7.0 V are applied, regardless of the supply voltage.

#### **Features**

- High Speed:  $t_{PD} = 3.8 \text{ ns (Typ)} @ V_{CC} = 5.0 \text{ V}$
- Low Power Dissipation:  $I_{CC} = 1 \mu A \text{ (Max)}$  at  $T_A = 25 \text{°C}$
- Power Down Protection Provided on inputs
- Balanced Propagation Delays
- Overvoltage Tolerant (OVT) Input and Output Pins
- Ultra-Small Packages
- These are Pb-Free Devices

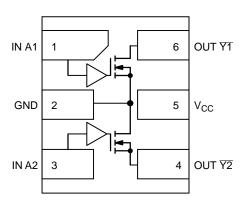


Figure 1. Pinout (Top View)

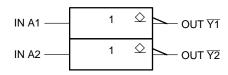


Figure 2. Logic Symbol

# **PIN ASSIGNMENT**

1	IN A1
2	GND
3	IN A2
4	OUT Y2
5	V <sub>CC</sub>
6	OUT Y1

### **FUNCTION TABLE**

Α	7
L	Z
H	L



# ON Semiconductor®

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# MARKING DIAGRAMS



UDFN6 1.0 x 1.0 CASE 517BX





UDFN6 1.2 x 1.0 CASE 517AA





UDFN6 1.45 x 1.0 CASE 517AQ



F = Device Marking M = Date Code

### **ORDERING INFORMATION**

See detailed ordering and shipping information in the package dimensions section on page 4 of this data sheet.

# **MAXIMUM RATINGS**

Symbol	Parameter	Value	Unit	
V <sub>CC</sub>	DC Supply Voltage		-0.5 to +7.0	V
V <sub>IN</sub>	DC Input Voltage		-0.5 to +7.0	V
V <sub>OUT</sub>	DC Output Voltage		-0.5 to +7.0	V
I <sub>IK</sub>	DC Input Diode Current	V <sub>IN</sub> < GND	-20	mA
l <sub>ok</sub>	DC Output Diode Current	V <sub>OUT</sub> < GND	±20	mA
I <sub>O</sub>	DC Output Source/Sink Current	±12.5	mA	
I <sub>CC</sub>	DC Supply Current Per Supply Pin	±25	mA	
I <sub>GND</sub>	DC Ground Current per Ground Pin	±25	mA	
T <sub>STG</sub>	Storage Temperature Range	-65 to +150	°C	
TL	Lead Temperature, 1 mm from Case for 10 Second	s	260	°C
TJ	Junction Temperature Under Bias		150	°C
MSL	Moisture Sensitivity		Level 1	
F <sub>R</sub>	Flammability Rating Oxygen	Index: 28 to 34	UL 94 V-0 @ 0.125 in	
I <sub>LATCHUP</sub>	Latchup Performance Above V <sub>CC</sub> and Below GND	at 125 °C (Note 2)	±500	mA

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

1. Measured with minimum pad spacing on an FR4 board, using 10 mm-by-1 inch, 2 ounce copper trace no air flow.

2. Tested to EIA / JESD78.

# **RECOMMENDED OPERATING CONDITIONS**

Symbol	Parameter	Min	Max	Unit
V <sub>CC</sub>	Positive DC Supply Voltage		5.5	V
V <sub>IN</sub>	Digital Input Voltage		5.5	V
V <sub>OUT</sub>	Output Voltage	0	5.5	V
T <sub>A</sub>	Operating Free–Air Temperature		+125	°C
Δt/ΔV	Input Transition Rise or Fall Rate $ \begin{array}{c} V_{CC} = 3.3 \ V \pm 0.3 \ V \\ V_{CC} = 5.0 \ V \pm 0.5 \ V \end{array} $	0	100 20	ns/V

### DC ELECTRICAL CHARACTERISTICS

			Vec	V <sub>CC</sub> T <sub>A</sub> = 25 °C		°C T <sub>A</sub> = +85°C		+85°C	T <sub>A</sub> = -55°C to +125°C			
Symbol	Parameter	Conditions	(V)	Min	Тур	Max	Min	Max	Min	Max	Unit	
V <sub>IH</sub>	Low-Level Input Voltage		1.65	0.75 x V <sub>CC</sub>			0.75 x V <sub>CC</sub>				V	
			2.3 to 5.5	0.70 x V <sub>CC</sub>			0.70 x V <sub>CC</sub>					
V <sub>IL</sub>	Low-Level Input Voltage		1.65			0.25 x V <sub>CC</sub>		0.25 x V <sub>CC</sub>		0.25 x V <sub>CC</sub>	V	
			2.3 to 5.5			0.30 x V <sub>CC</sub>		0.30 x V <sub>CC</sub>		0.30 x V <sub>CC</sub>		
V <sub>OL</sub>	Low-Level Output Voltage	$V_{IN} = V_{IH} \text{ or } V_{IL}$ $I_{OL} = 50  \mu\text{A}$	2.0 3.0 4.5		0 0 0	0.1 0.1 0.1		0.1 0.1 0.1		0.1 0.1 0.1	V	
		$V_{IN} = V_{IH}$ or $V_{IL}$ $I_{OL} = 4$ mA $I_{OL} = 8$ mA	3.0 4.5			0.36 0.36		0.44 0.44		0.52 0.52		
I <sub>LKG</sub>	Z-State Output Leakage Current	V <sub>IN</sub> = V <sub>IH</sub> , V <sub>OUT</sub> = V <sub>CC</sub> or GND	5.5			±0.25		±2.5		±5.0	μΑ	
I <sub>IN</sub>	Input Leakage Current	$0 \le V_{IN} \le 5.5 V$	0 to 5.5			±0.1		±1.0		±1.0	μΑ	
l <sub>OFF</sub>	Power Off Input Leakage Current	$0 \le V_{IN},$ $V_{OUT} \le 5.5 V$	0			0.25		2.5		5.0	μΑ	
I <sub>CC</sub>	Quiescent Supply Current	$0 \le V_{IN} \le V_{CC}$	5.5			1.0		10		40	μΑ	

# AC ELECTRICAL CHARACTERISTICS (Input $t_r = t_f = 3.0 \text{ nS}$ )

		V <sub>CC</sub>	Test		T <sub>A</sub> = 25	°C	T <sub>A</sub> =	+85°C		–55°C  25°C	
Symbol	Parameter	(V)	Condition	Min	Тур	Max	Min	Max	Min	Max	Unit
t <sub>PZL</sub>	Propagation Delay, Input A to Output $\overline{Y}$	3.0 to 3.6	$R_L = R_1 = 50 \Omega$ $C_L = 15 pF$		5.0	7.1		8.5		10	ns
			$R_L = R_1 = 50 \Omega$ $C_L = 50 pF$		7.5	10.6		12		14.5	
		4.5 to 5.5	$R_L = R_1 = 50 \Omega$ $C_L = 15 pF$		3.8	5.5		6.5		8.0	
			$R_L = R_1 = 50 \Omega$ $C_L = 50 \text{ pF}$		5.3	7.5		8.5		10	
t <sub>PLZ</sub>	Output Disable Time	3.0 to 3.6	$R_L = R_1 = 50 \Omega$ $C_L = 50 pF$		7.5	10.6		12		14.5	ns
		4.5 to 55	$R_L = R_1 = 50 \Omega$ $C_L = 50 pF$		5.3	7.5		8.5		10	
C <sub>IN</sub>	Input Capacitance				4.0	10		10		10	pF
C <sub>PD</sub>	Power Dissipation Capacitance (Note 3)	5.0			18						pF

<sup>3.</sup> C<sub>PD</sub> is defined as the value of the internal equivalent capacitance which is calculated from the dynamic operating current consumption without load. Average operating current can be obtained by the equation I<sub>CC(OPR)</sub> = C<sub>PD</sub> • V<sub>CC</sub> • f<sub>in</sub> + I<sub>CC</sub>. C<sub>PD</sub> is used to determine the no–load dynamic power consumption: P<sub>D</sub> = C<sub>PD</sub> • V<sub>CC</sub><sup>2</sup> • f<sub>in</sub> + I<sub>CC</sub> • V<sub>CC</sub>.

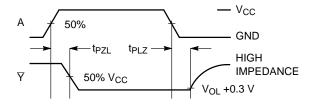
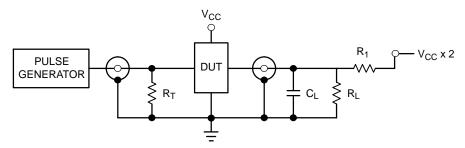


Figure 3. Switching Waveforms



 $R_T = Z_{OUT}$  of pulse generator (typically 50  $\Omega$ )

Figure 4. Test Circuit

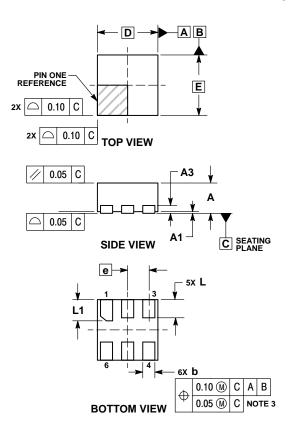
# **ORDERING INFORMATION**

Device	Package	Shipping <sup>†</sup>
NLU2G06MUTCG	UDFN6, 1.2 x 1.0, 0.4P (Pb-Free)	3000 / Tape & Reel
NLU2G06AMUTCG (In Development)	UDFN6, 1.45 x 1.0, 0.5P (Pb-Free)	3000 / Tape & Reel
NLU2G06CMUTCG (In Development)	UDFN6, 1.0 x 1.0, 0.35P (Pb-Free)	3000 / Tape & Reel

<sup>†</sup>For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

### **PACKAGE DIMENSIONS**

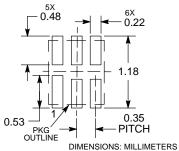
UDFN6 1.0x1.0, 0.35P CASE 517BX ISSUE O



- NOTES:
  1. DIMENSIONING AND TOLERANCING PER
- DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
   CONTROLLING DIMENSION: MILLIMETERS.
   DIMENSION b APPLIES TO PLATED TERMINAL AND IS MEASURED BETWEEN 0.15 AND 0.20 MM FROM TERMINAL TIP.
   PACKAGE DIMENSIONS EXCLUSIVE OF BURRS AND MOLD FLASH.

	MILLIMETERS					
DIM	MIN	MAX				
Α	0.45	0.55				
A1	0.00	0.05				
A3	0.13	REF				
b	0.12	0.22				
D	1.00 BSC					
Е	1.00	BSC				
е	0.35	BSC				
L	0.25	0.35				
L1	0.30	0.40				

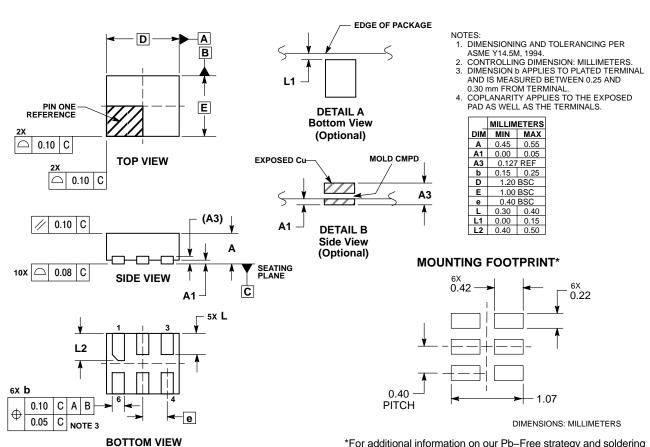
# RECOMMENDED SOLDERING FOOTPRINT\*



\*For additional information on our Pb–Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

# **PACKAGE DIMENSIONS**

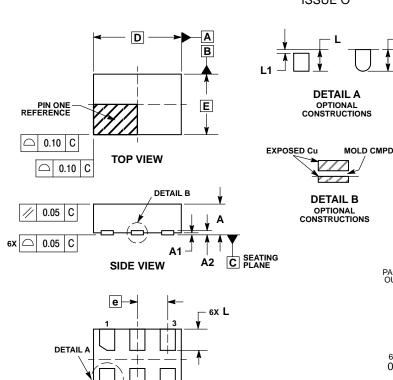
## UDFN6, 1.2x1.0, 0.4P CASE 517AA ISSUE C



<sup>\*</sup>For additional information on our Pb–Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

# PACKAGE DIMENSIONS

### UDFN6 1.45x1.0, 0.5P CASE 517AQ **ISSUE O**



0.10 С A B

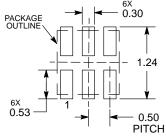
С 0.05

NOTE 3

- NOTES:
  1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
- CONTROLLING DIMENSION: MILLIMETERS.
  DIMENSION b APPLIES TO PLATED TERMINAL
- AND IS MEASURED BETWEEN 0.15 AND 0.30 mm FROM THE TERMINAL TIP.

	MILLIMETERS					
DIM	MIN	MAX				
Α	0.45	0.55				
A1	0.00	0.05				
A2	0.07 REF					
b	0.20	0.30				
D	1.45 BSC					
Е	1.00 BSC					
е	0.50 BSC					
L	0.30	0.40				
L1		0.15				

#### **MOUNTING FOOTPRINT**



**DIMENSIONS: MILLIMETERS** 

\*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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